WHAT IS CLAIMED IS:

1. A solid-state image pickup device comprising:

a circuit board having an opening;

a sensor package, disposed at one surface of the circuit board so that a light-receiving surface of a solid-state image pickup element opposes the opening, for sealing in the solid-state image pickup element; and

an optical unit disposed at the other surface of the circuit board so that incident light is focused on the light-receiving surface.

2. A solid-state image pickup device according to Claim 1, wherein the sensor package includes a signal processing circuit for processing a signal of the solid-state image pickup element.

3. A solid-state image pickup device according to Claim 1, wherein the solid-state image pickup element has a signal processing function.

4. A solid-state image pickup device according to Claim 1, wherein the circuit board is connected to an external device without a connector.

5. A method of producing a solid-state image pickup device comprising the steps of:

providing a circuit board with an opening;

joining a sensor package, in which a solid-state image pickup element has been previously sealed, to one surface of the circuit board so that a light-receiving surface of the solid-state image pickup element opposes the opening; and

disposing and joining an optical unit at and to the other surface of the circuit board so that incident light is focused on the light-receiving surface.

6. A method of producing a solid-state image pickup device according to Claim 5, wherein the sensor package includes a signal processing circuit for processing a signal of the solid-state image pickup element.

7. A method of producing a solid-state image pickup device according to Claim 5, wherein the solid-state image pickup element has a signal processing function.

8. A method of producing a solid-state image pickup device according to Claim 5, wherein the circuit board is connected to an external device without a connector.